

To all our customers

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The semiconductor operations of Mitsubishi Electric and Hitachi were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Hitachi, Hitachi, Ltd., Hitachi Semiconductors, and other Hitachi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HVC300C

Variable Capacitance Diode for VHF tuner



ADE-208-1611 (Z)

Rev.0
Feb. 2003

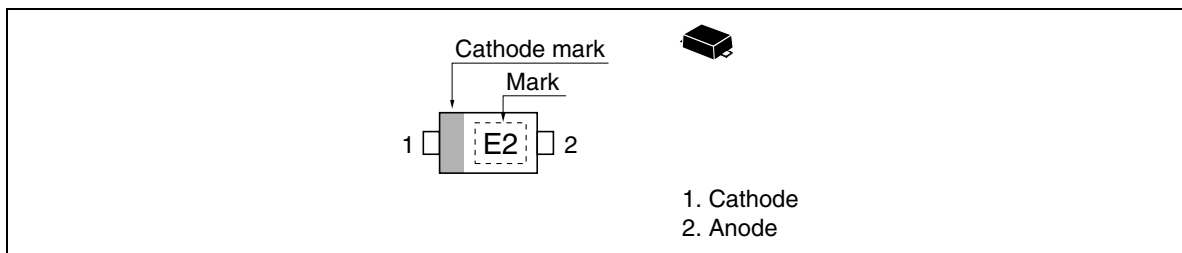
Features

- High capacitance ratio ($n = 14.5$ min) and suitable for wide band tuner.
- Low series resistance and good C-V linearity.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC300C	E2	UFP

Pin Arrangement



HVC300C

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	V_{RM}^{*1}	35	V
Reverse voltage	V_R	34	V
Junction temperature	Tj	150	°C
Storage temperature	Tstg	–55 to +150	°C

Note: 1. $R_L = 10\text{ k}\Omega$

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_{R1}	—	—	10	nA	$V_R = 32\text{ V}$
	I_{R2}	—	—	100		$V_R = 32\text{ V}$, Ta = 60°C
Capacitance	C_2	39.5	—	47.0	pF	$V_R = 2\text{ V}$, f = 1 MHz
	C_{25}	2.6	—	3.0		$V_R = 25\text{ V}$, f = 1 MHz
Capacitance ratio	n	14.5	—	—	—	C_2 / C_{25}
Series resistance	r_s	—	—	1.1	Ω	$V_R = 5\text{ V}$, f = 470 MHz
Matching error	$\Delta C/C^{*1}$	—	—	2.0	%	$V_R = 2\text{ to }25\text{ V}$, f = 1 MHz

Note: 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of $\Delta C/C$ continuous in a reel, expect extension to another group.

Calculate Matching Error,

$$\Delta C/C = \frac{(C_{\max} - C_{\min})}{C_{\min}} \times 100 (\%)$$

Main Characteristic

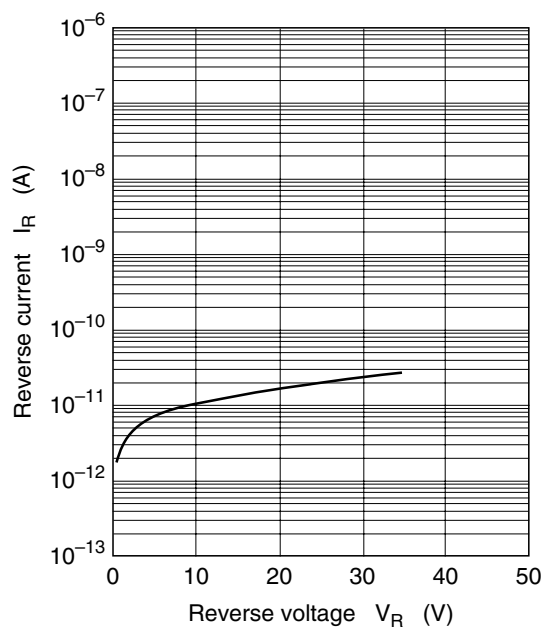


Fig.1 Reverse current vs. Reverse voltage

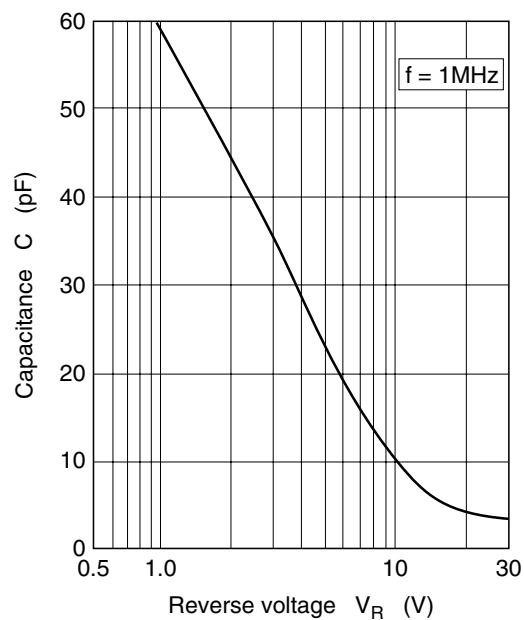


Fig.2 Capacitance vs. Reverse voltage

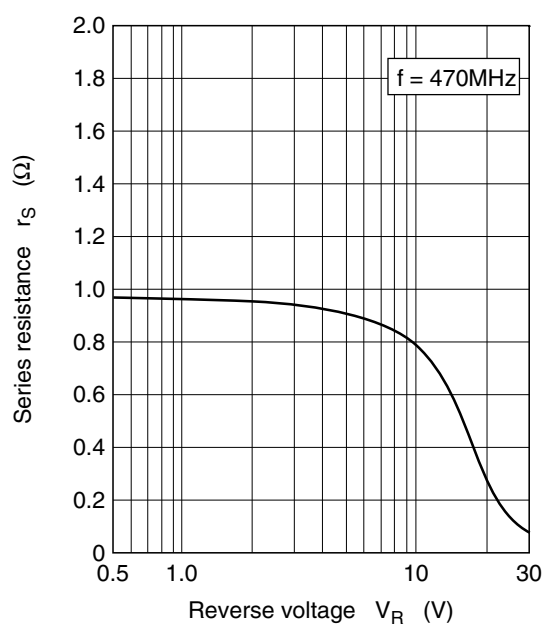


Fig.3 Series resistance vs. Reverse voltage

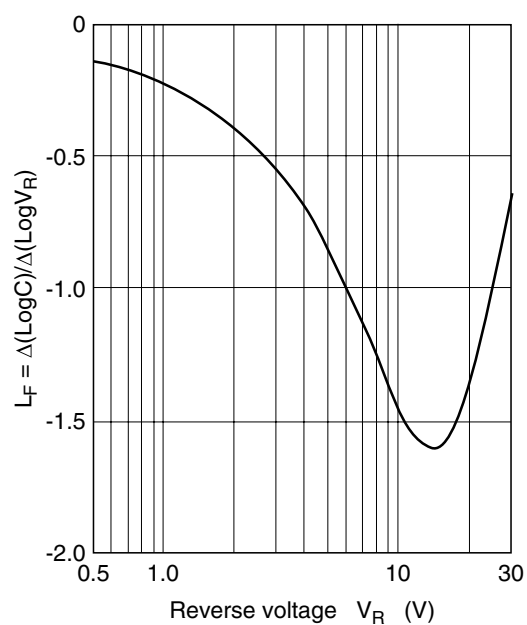
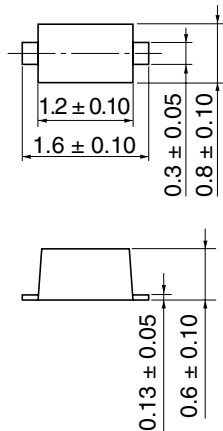


Fig.4 Linearity factor vs. Reverse voltage

HVC300C

Package Dimensions

As of July, 2002
Unit: mm



Hitachi Code	UFP
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.0016 g

Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

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